



BSI Standards Publication

Circuit boards and circuit board assemblies — Design and use

Part 6-2: Land pattern design — Description of land pattern for the most common surface mounted components (SMD)

National foreword

This British Standard is the UK implementation of EN IEC 61188-6-2:2021. It is identical to IEC 61188-6-2:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Date	Text affected
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English Version

Circuit boards and circuit board assemblies - Design and use -
Part 6-2: Land pattern design - Description of land pattern for the
most common surface mounted components (SMD)
(IEC 61188-6-2:2021)

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-2: Conception de la zone
de report - Description de la zone de report pour les
composants montés en surface (CMS) les plus courants
(IEC 61188-6-2:2021)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-2: Anschlussflächenbild - Beschreibung
des Anschlussflächenbilds für die meisten
oberflächenmontierbaren Bauelemente (SMD, en: surface
mounted components)
(IEC 61188-6-2:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1637/CDV, future edition 1 of IEC 61188-6-2, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61188-6-2:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-11
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-03-11

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61188-5-1:2002	NOTE	Harmonized as EN 61188-5-1:2002 (not modified)
IEC 61188-5-2	NOTE	Harmonized as EN 61188-5-2
IEC 61188-5-3	NOTE	Harmonized as EN 61188-5-3
IEC 61188-5-4	NOTE	Harmonized as EN 61188-5-4
IEC 61188-5-5	NOTE	Harmonized as EN 61188-5-5
IEC 61188-5-6	NOTE	Harmonized as EN 61188-5-6
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8
IEC 61191 (series)	NOTE	Harmonized as EN 61191 (series)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61188-6-1	-	Circuit boards and circuit board assemblies - Design and use - Part 6-1: Land pattern design - Generic requirements for land pattern on circuit boards	EN IEC 61188-6-1 ¹	-
IEC 61188-6-4	-	Printed boards and printed board assemblies - Design and use - Part 6-4: Land pattern design - Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design	EN IEC 61188-6-4	-
IEC 61191-2	2017	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	2017

¹ To be published. Stage at the time of publication: prEN IEC 61188-6-1:2020.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES –
DESIGN AND USE –****Part 6-2: Land pattern design – Description of land pattern
for the most common surface mounted components (SMD)**

FOREWORD

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IEC 61188-6-2 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1637/CDV	91/1657/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 61188 series, published under the general title *Circuit boards and circuit board assemblies – Design and use*, can be found on the IEC website.

Future documents in this series will carry the new general title as cited above. Titles of existing documents in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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